

SOT605-1

plastic, thermal enhanced ball grid array package; 600 balls;
1.27 mm pitch; 40 mm x 40 mm x 0.9 mm body

25 September 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA600
Package type industry code	HBGA600
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	17-03-2003
Manufacturer package code	SOT605

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	39.8	40	40.2	mm
package width	39.8	40	40.2	mm
seated height	-	1.65	1.65	mm
package height	0.8	0.9	1	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	600	-	



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2 Package outline

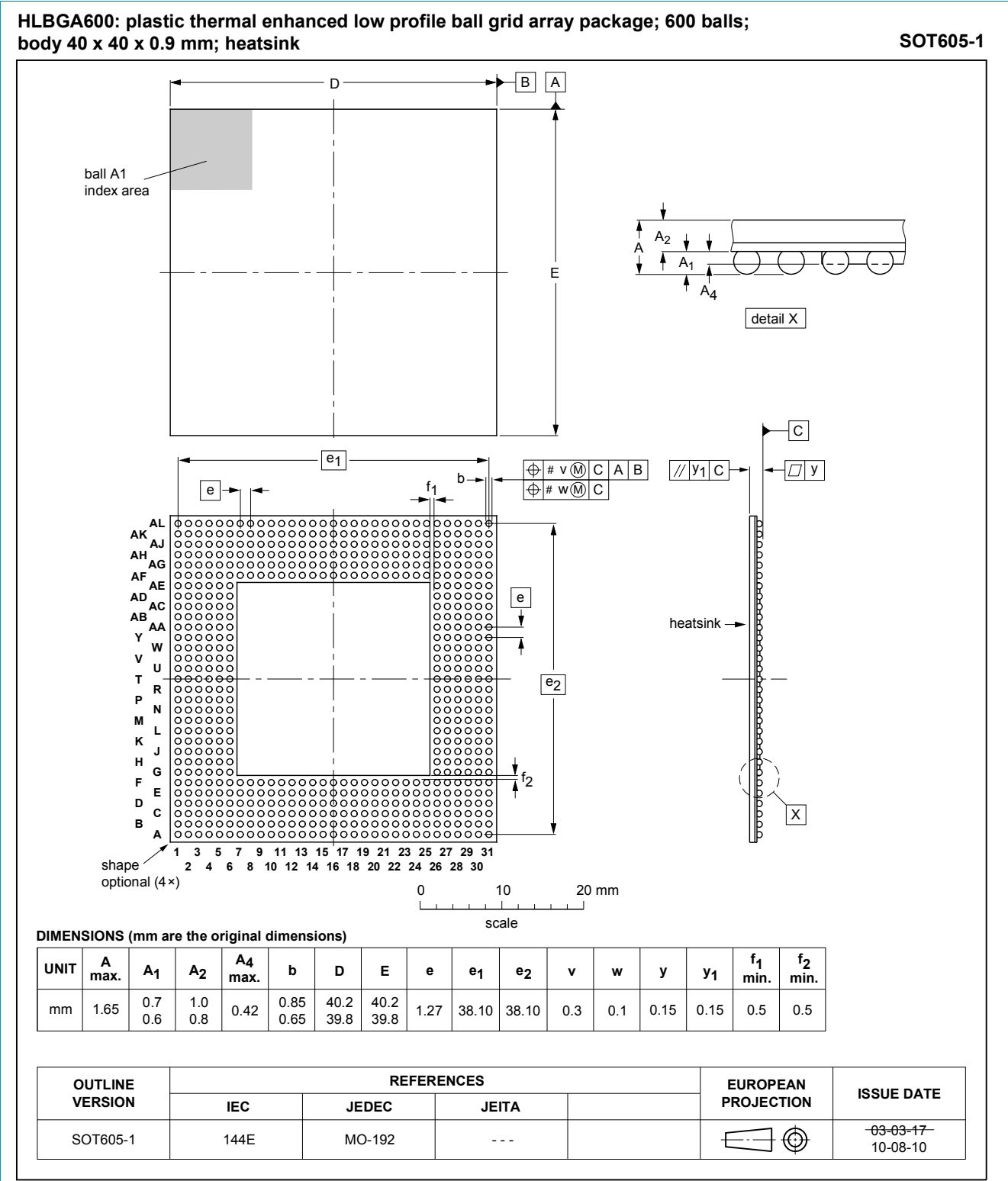


Figure 1. Package outline HLBGA600 (SOT605-1)

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3 Soldering

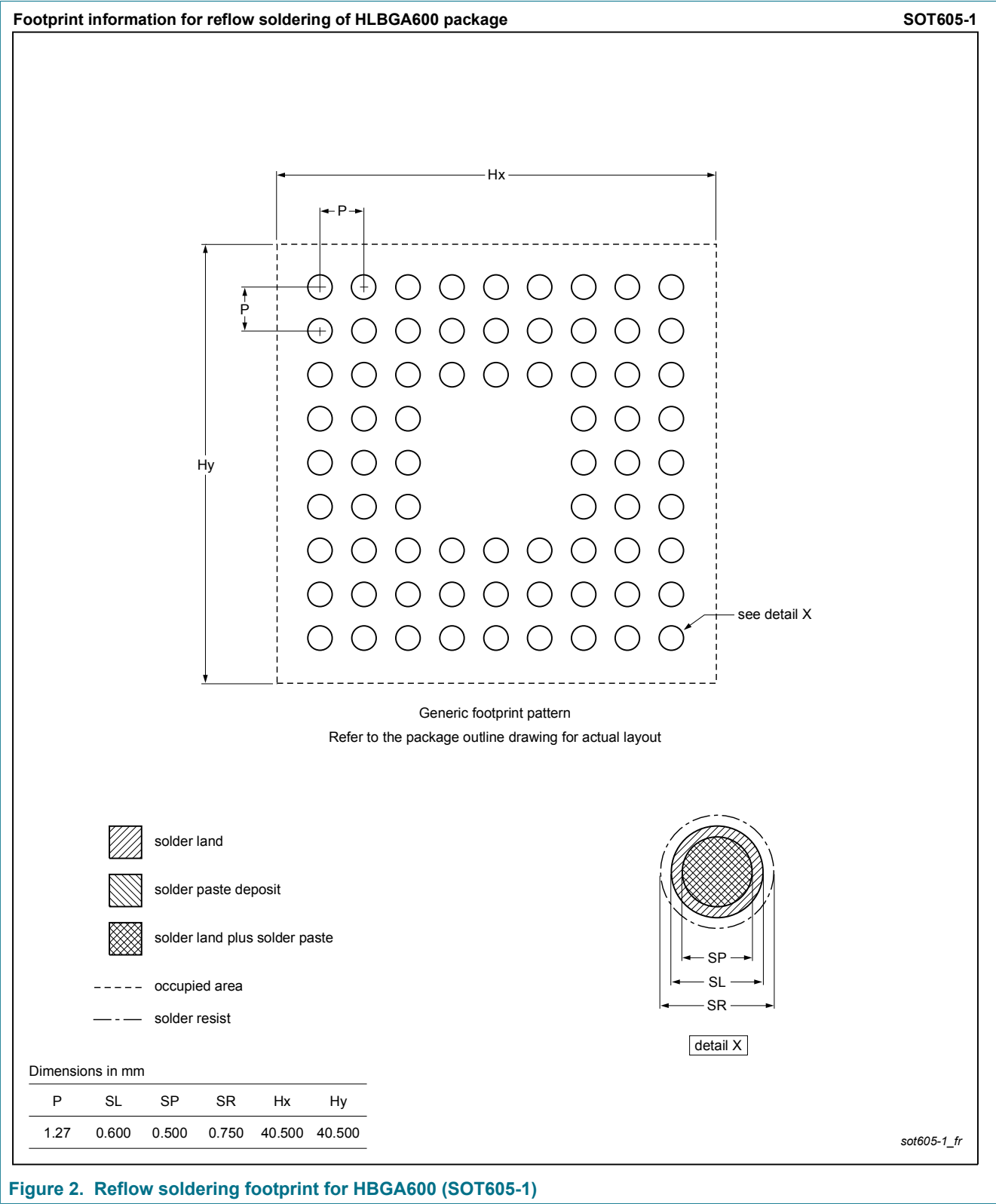


Figure 2. Reflow soldering footprint for HBLGA600 (SOT605-1)

4 Legal information

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